

General Description

- Trench Power AlphaMOS-II technology
- Low $R_{DS(ON)}$
- Low C_{iss} and C_{rss}
- High Current Capability
- RoHS and Halogen Free Compliant

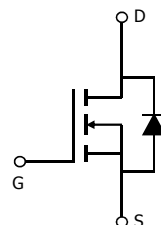
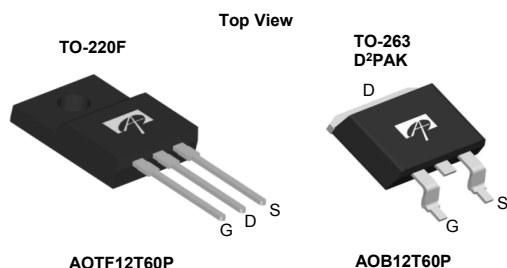
Applications

- General Lighting for LED and CCFL
- AC/DC Power supplies for Industrial, Consumer, and Telecom

Product Summary

$V_{DS} @ T_{j,max}$	700V
I_{DM}	48A
$R_{DS(ON),max}$	< 0.52 Ω
$Q_{g,typ}$	33nC
$E_{oss} @ 400V$	4.4 μ J

100% UIS Tested
100% R_g Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOB12T60PL	TO-263 Green	Tape & Reel	800
AOTF12T60P	TO-220F Pb Free	Tube	1000
AOTF12T60PL	TO-220F Green	Tube	1000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter		Symbol	AOB12T60P	AOTF12T60P	AOTF12T60PL	Units
Drain-Source Voltage		V _{DS}	600			V
Gate-Source Voltage		V _{GS}	±30			V
Continuous Drain Current	T _C =25°C	I _D	12	12*	12*	A
	T _C =100°C		9	9*	9*	
Pulsed Drain Current ^C		I _{DM}	48			
Avalanche Current ^C L=1mH		I _{AR}	12			A
Repetitive avalanche energy ^C		E _{AR}	72			mJ
Single pulsed avalanche energy ^G		E _{AS}	750			mJ
MOSFET dv/dt ruggedness		dv/dt	50			V/ns
Peak diode recovery dv/dt ^J			15			
Power Dissipation ^B	T _C =25°C	P _D	250	50	35	W
	Derate above 25°C		2	0.4	0.3	W/°C
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150			°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds		T _I	300			°C

Thermal Characteristics

Parameter	Symbol	AOB12T60P	AOTF12T60P	AOTF12T60PL	Units
Maximum Junction-to-Ambient ^{A,D}	$R_{\theta JA}$	65	65	65	$^\circ\text{C/W}$
Maximum Case-to-sink ^A	$R_{\theta CS}$	0.5	---	---	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{\theta JC}$	0.5	2.5	3.6	$^\circ\text{C/W}$

* Drain current limited by maximum junction temperature.

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V, T _J =25°C	600			V
		I _D =250μA, V _{GS} =0V, T _J =150°C		700		
BV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, V _{GS} =0V		0.58		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{GS} =0V			1	μA
		V _{DS} =480V, T _J =125°C			10	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±30V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	3	4.1	5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =6A		0.44	0.52	Ω
g _{FS}	Forward Transconductance	V _{DS} =40V, I _D =6A		11		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.73	1	V
I _S	Maximum Body-Diode Continuous Current				12	A
I _{SM}	Maximum Body-Diode Pulsed Current ^C				48	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		2028		pF
C _{oss}	Output Capacitance			71		pF
C _{o(er)}	Effective output capacitance, energy related ^H	V _{GS} =0V, V _{DS} =0 to 480V, f=1MHz		52		pF
C _{o(tr)}	Effective output capacitance, time related ^I			94		pF
C _{rss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		13		pF
R _g	Gate resistance	f=1MHz		2.2		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =480V, I _D =12A		33	50	nC
Q _{gs}	Gate Source Charge			13		nC
Q _{gd}	Gate Drain Charge			10		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =300V, I _D =12A, R _G =25Ω		52		ns
t _r	Turn-On Rise Time			72		ns
t _{D(off)}	Turn-Off DelayTime			66		ns
t _f	Turn-Off Fall Time			42		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =12A, dI/dt=100A/μs, V _{DS} =100V		483		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =12A, dI/dt=100A/μs, V _{DS} =100V		7		μC

A. The value of R_{θJA} is measured with the device in a still air environment with T_A=25° C.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C, Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 ms pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. L=60mH, I_{AS}=5A, V_{DD}=150V, R_G=25Ω, Starting T_J=25° C.

H. C_{o(er)} is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

I. C_{o(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

J. I_{SD}≤I_D, dI/dt≤200A/μs, V_{DD}=400V, T_J≤T_{J(MAX)}.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

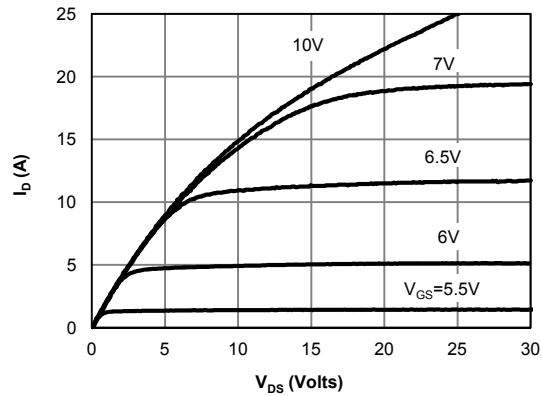


Figure 1: On-Region Characteristics

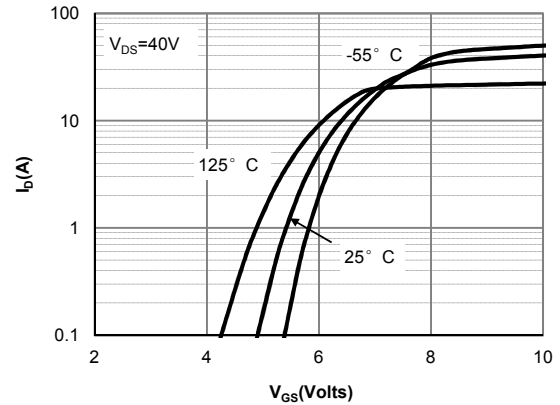


Figure 2: Transfer Characteristics

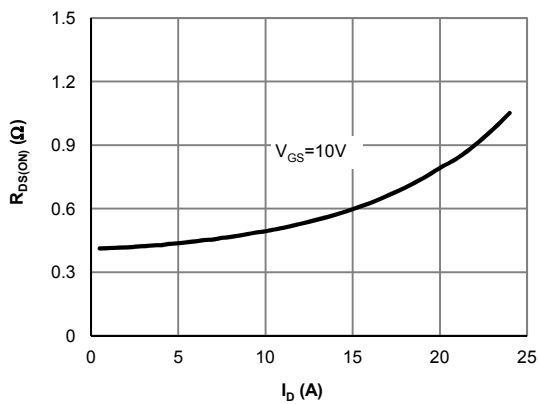


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

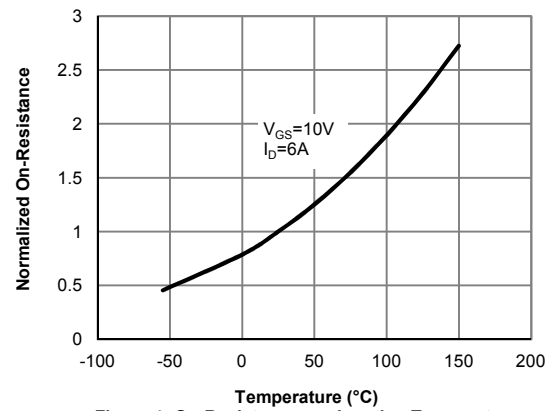


Figure 4: On-Resistance vs. Junction Temperature

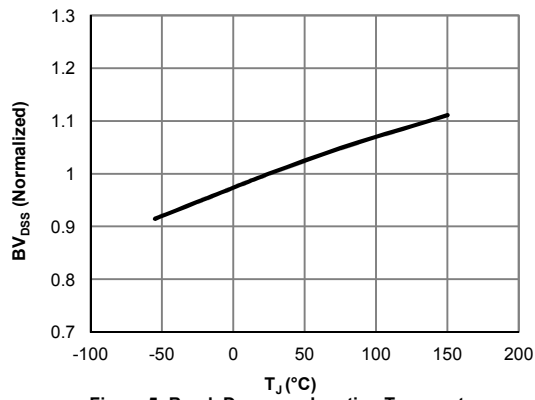


Figure 5: Break Down vs. Junction Temperature

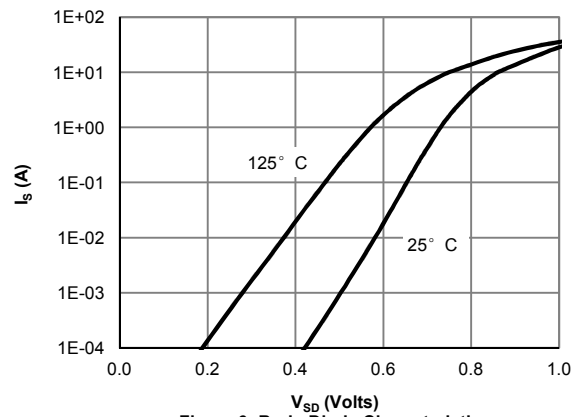
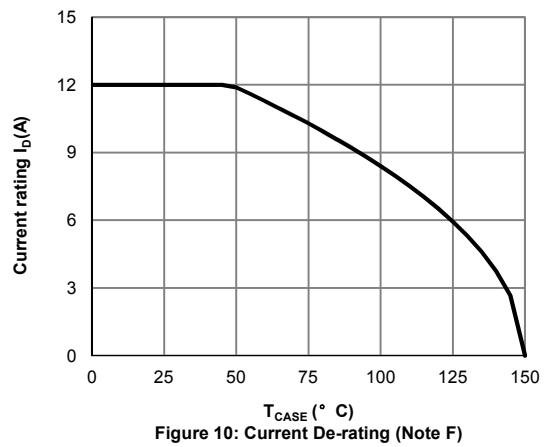
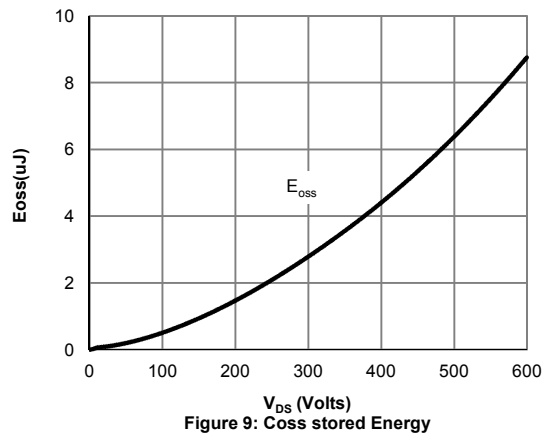
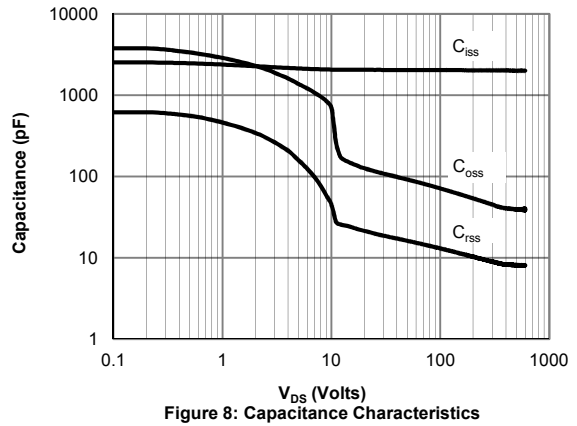
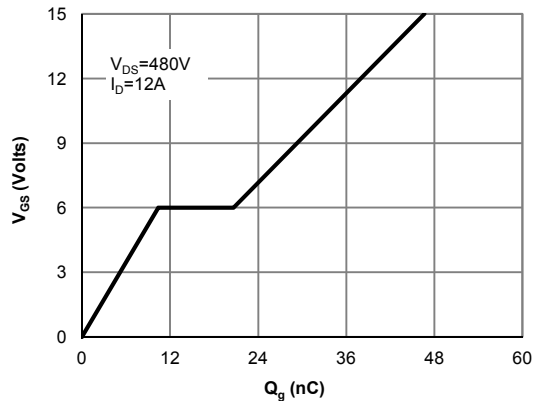


Figure 6: Body-Diode Characteristics

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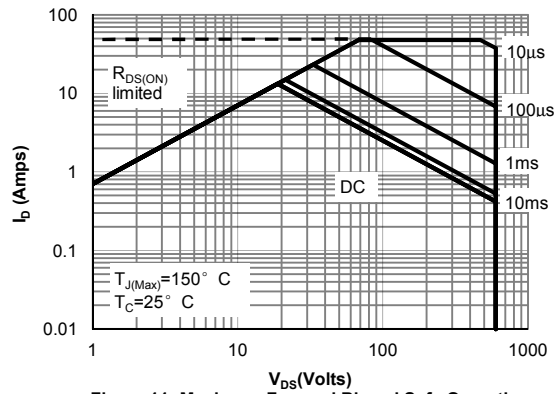


Figure 11: Maximum Forward Biased Safe Operating Area for TO-263 (Note F)

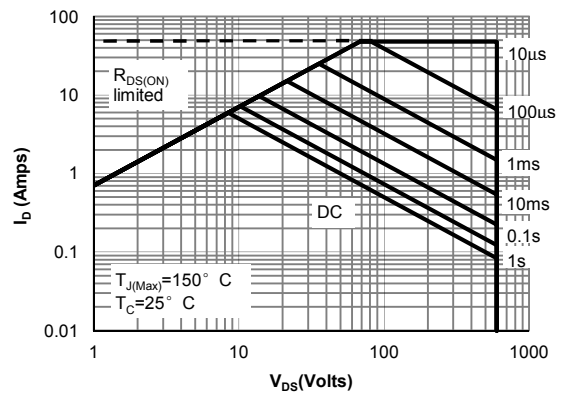


Figure 12: Maximum Forward Biased Safe Operating Area for TO-220F Pb Free (Note F)

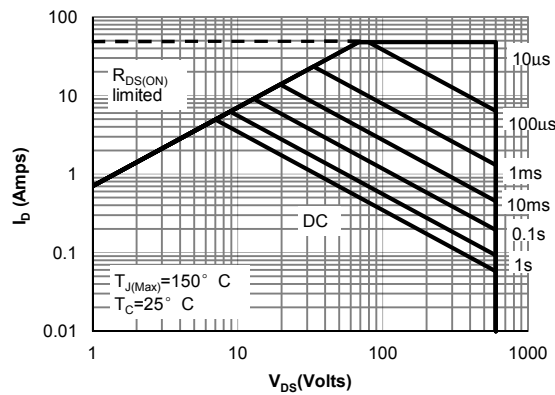
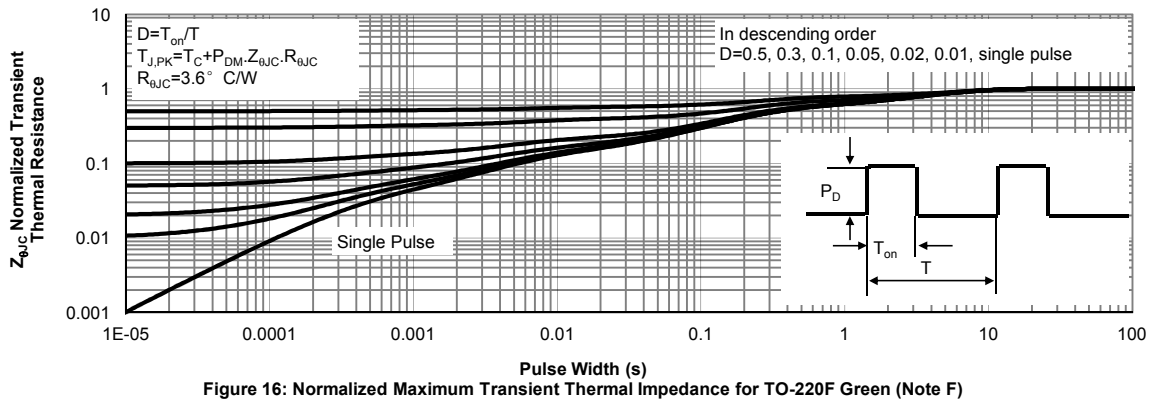
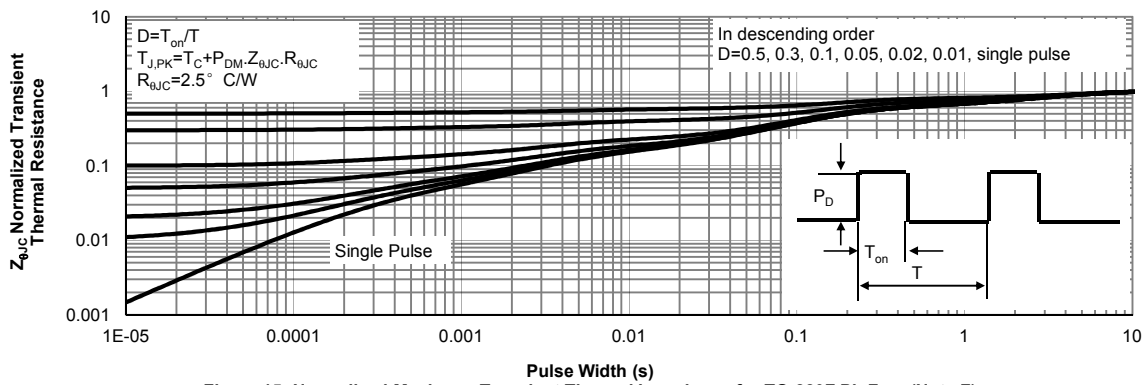
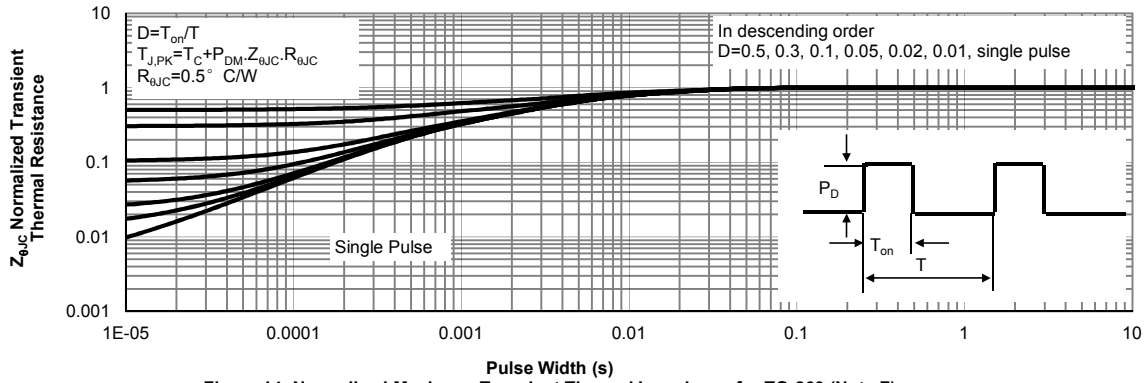
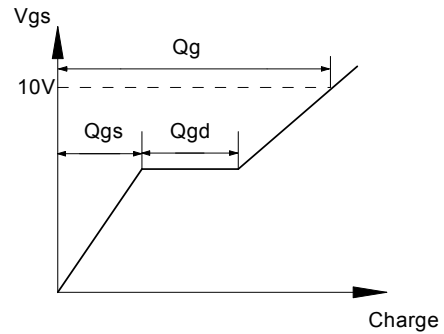
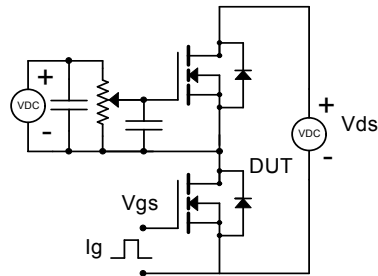


Figure 13: Maximum Forward Biased Safe Operating Area for TO-220F Green (Note F)

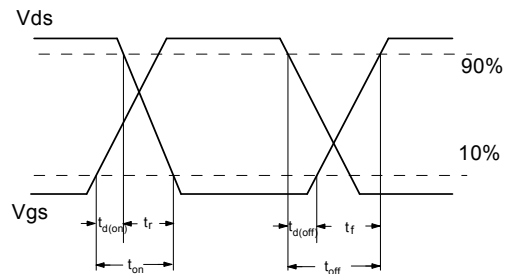
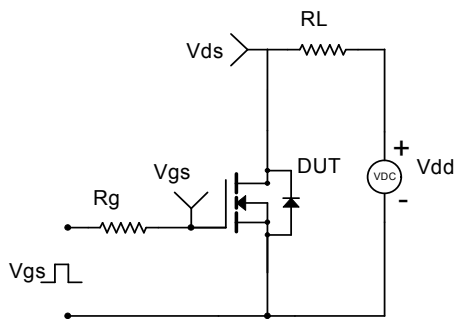
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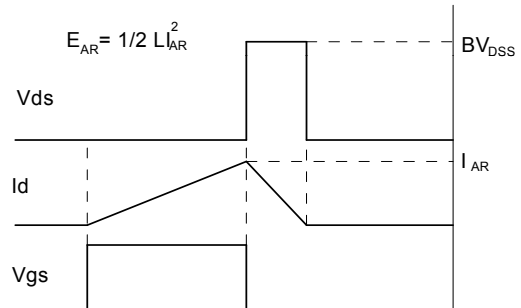
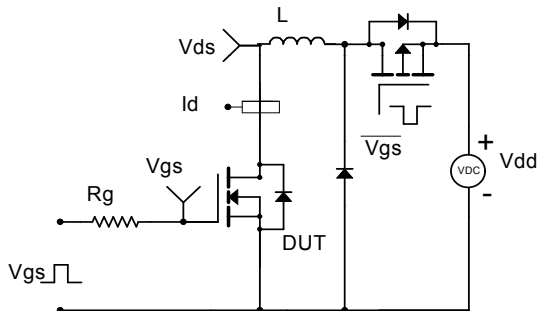
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

